

CLAIMS

1. A curable resin composition being curable through at least two types of curing reactions, the curable resin composition comprising:
 - a curable component (A1) that contracts in volume through one curing reaction; and
 - a curable component (B1) that contracts in volume through another curing reaction,wherein the one curing reaction is an ionic ring-opening polymerization reaction or a polyaddition polymerization reaction, and the other curing reaction is a radical addition polymerization reaction,
 - wherein a volume contraction ratio A (%) of the curable component (A1) that is cured through the ionic ring-opening polymerization reaction or the polyaddition polymerization reaction to contract in volume is within a range of $0 < A \leq 7$, and
 - wherein a volume contraction ratio B (%) of the curable component (B1) that is cured through the radical addition polymerization reaction to contract in volume is within a range of $5 \leq B \leq 30$, and
 - wherein the volume contraction ratio A and the volume contraction ratio B satisfy an expression below:
 $A < B$.
2. The curable resin composition according to claim 1, wherein the ionic ring-opening polymerization reaction or the polyaddition polymerization reaction is a thermal ionic ring-opening polymerization reaction or a thermal polyaddition polymerization reaction, and the radical addition polymerization reaction is a photo radical addition polymerization reaction.
3. The curable resin composition according to claim 1 or 2, wherein the curable resin composition is used for forming a warpage correction layer that is disposed on a face opposite to a face on which a redistribution layer of a fan-out wafer level package is disposed.